MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

H−PSOF8L 9.90x11.68, 1.20P
CASE 100DC
ISSUE A

DATE 18 MAY 2023

DOCUMENT NUMBER: 98AON80466G
DESCRIPTION: H−PSOF8L 9.90x11.68, 1.20P

NOTE:
1. PACKAGE STANDARD REFERENCE: JEDEC MD-296, ISSUE A.
3. CONTROLLING DIMENSIONS: MILLIMETERS.
4. COPLANARITY APPLIES TO THE EXPOSED WELL AS THE TERMINALS.
5. DIMENSIONS D1 AND D2 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
6. SEATING PLANE IS DEFINED BY THE TERMINALS. "A" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

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